16th European Wet & 45th European CMP Users Meeting

Wet-Session: Thursday, April 20, 2023, 13:00 – 17:40

CMP-Session: Friday, April 21, 2023, 2022, 8:00 – 13:05

OST – Ostschweizer Fachhochschule, Buchs, Switzerland

Organized by European CMP&WET Usergroup

Agenda Thursday

13:00 Welcome Coffee, Tea, Softdrinks

13:30 Opening Remarks & Welcome from OST
Knut Gottfried & OST Representative
Fraunhofer ENAS & ErzM-Technologies, Chemnitz, Germany

13:50 **Tutorial:** "Wet cleaning - from the beginning to now"
Don Dussault
ProSys Megasonics, Stockach, Germany

Wet Processes: Session 1
Session Chair: Marie Wolff, Fraunhofer ISIT, Itzehoe, Germany

14:35 Reduced time-to-production after equipment delivery
Stefan Zürcher
AP&S International GmbH, Donaueschingen, Germany

14:55 Systematic Process Technology selection for SiC containing waste water
Jochen Ruth
Pall GmbH, Dreieich, Germany

Coffee Break

Wet Processes: Session 2
Session Chair: Gerfried Zwicker, zwickerconsult, Berlin, Germany

15:40 Wet Chemical Solutions for SiC Surface Treatment
Norbert Bay / Rahim Hamid
Rena Technologies GmbH, Gütenbach, Germany

16:00 On-wafer surface enhanced Raman spectroscopy and its application for UPW defectivity analysis
Ali Ozhan Altun
UNISERS AG, Zürich, Switzerland

16:20 State-of-the Art Filtration for Semiconductor Applications
Sebastian Dilly
Pall GmbH, Dreieich, Germany

16:40 Non-invasive ultrasonic flow measurement systems for WET and CMP applications
Anika Baumhauer
SONOTEC GmbH, Halle (Saale), Germany

17:00 UPW Filtration Best Practice
Jochen Ruth
Pall GmbH, Dreieich, Germany

17:20 QUAVA Mega Puck - High Performance Cleaning System
Francisco Javier Lopez-Guzman
Kaijo, Wiesbaden, Germany

17:40 End of Wet Users Meeting / time for networking and discussion

19:15 Conference Dinner at Buchserhof Hotel

Agenda Friday

8:00 Good Morning Coffee, Tea, Softdrinks

8:15 Opening Remarks
Knut Gottfried
Fraunhofer ENAS & ErzM-Technologies, Chemnitz, Germany

8:20 **Tutorial:** General CMP Introduction
Mario Stella
Entegris/CMC Materials, Wales / Vale of Glamorgan, United Kingdom

CMP Processes: Session 1
Session Chair: Martin Kulawski, Advaplan, Espoo, Finland

9:10 CMP of SiGe-Substrates for Spin-Qubit Applications
Marko ListkerIHP, Frankfurt (Oder), Germany

9:30 Automatic Analysis of CMP Dishing in Via Arrays from AFM Images
Andreas Zienert
Fraunhofer ENAS, Chemnitz, Germany

9:50 Material Response in CMP Pad Conditioning
Scott Lawing
Kinik North America, Newark, Delaware, United States

Coffee Break

CMP Processes: Session 2
Session Chair: Catharina Rudolph, Fraunhofer IZM-ASSID, Dresden, Germany

10:30 CMP activities in North America
Bob Roberts
X-trinSiC Inc., Phoenix, AZ, United States

10:50 Can empirical physics models improve machine learning performance using planarization data?
Tom Rothe
Fraunhofer ENAS, Chemnitz, Germany

11:10 GRIN Pad Technology, the next step in high precision optics industrial polishing
Oliver Fähnle
Ostschweizer Fachhochschule, Buchs, Switzerland

11:30 Optical Endpoint Detection in CMP
Andre Lauff
Infineon, Dresden, Germany

11:50 Slurry recycling
Johannes Sporrer/ Andreas Dietrich
FÄTHGROUP, München, Germany

12:10 **Tutorial:** About pad conditioning
Scott Lawing
Kinik North America, Newark, Delaware, United States

13:05 End of CMP Users Meeting / time for networking and discussion